



PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

01-JUL-2001

SUBJECT: Product/Process Change Notification #11500

TITLE: Initial Notification for Assembly & Test Expansion for C-77 (TO-126) Packaged Devices

EFFECTIVE DATE: 19-Oct-2001

AFFECTED CHANGE CATEGORY: Subcontractor Assembly Site & Subcontractor Test Site

AFFECTED PRODUCT DIVISION: Bipolar Discretets Products Div

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers <S20636@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office
or Jose Ramirez<RVEG40@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Jose Ramirez <RVEG40@onsemi.com>

DISCLAIMER:

Initial Product/Process Change Notification (IPCN) -First Notification distributed to customers.
Distributed at least 120 days from the effective date of the change.

Final Product/Process Change Notification (FPCN) -Final Notification completing the notification
process. Distributed at least 60 days from the effective date of the change. ON Semiconductor will
consider this change approved unless specific conditions of acceptance are provided in writing within
30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semiconductor wishes to notify its Customers that the Assembly and Final Test Manufacturing
Operations for its Case 77 (TO-126) packaged Products currently done in Seremban, Malaysia, will be
expanded to Manila, Philippines at PSI. PSI is QS9000 certified and current subcontractor for ON
Semiconductor on several other plastic packages and one of the largest Assembly and Test sites in
the Asia/Pac region. ON Semiconductor continues to make substantial investments in both new
technologies and improved manufacturing capabilities to provide you the highest quality and reliability
in the Semiconductor industry. We believe these actions will also improve our ability to serve you
better in the future.



Product/Process Change Notification #11500

QUALIFICATION PLAN:

*Per AEC-Q101 guidelines.

Test*	Conditions	Exceptions
Parametric verification	Per device specification @ 25DegC	
HTRB	1000 hrs Vcb=80% T=150DegC	
Temp Cycle	1K cycles - 65DegC to 150DegC	
Autoclave	96 hrs RH=100% P=15psi Ta=121DegC	
H3TRB	1000 hrs Vcb=80% RH=85%	
IOL	15K cycles Dtj=100DegC	
D.P.A.	Random H3TRB & IOL samples	
Thermal Resistance		Delta VBE
Die Shear	Pre & Post process change comp.	
Wire Bond Strength	Pre & Post process change comp.	
Wire Bond Shear Method 3		

Qualification Vehicle Justification

Family	Qualification Device	Reason Chosen
PNP Bipolar Power	BD436T	Large Die size
NPN Bipolar Power	MJE340	Highest Voltage
Thyristors	2N6075B (Triac)	Highest voltage
Thyristors	MCR106-8 (SCR)	Highest voltage

RELIABILITY DATA SUMMARY: To be available prior to Final PCN.

ELECTRICAL CHARACTERISTIC SUMMARY: To be available prior to Final PCN.

CHANGED PART IDENTIFICATION:

Detailed device date code change information to be supplied with Final PCN.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

- 2N4918
- 2N4919
- 2N4920
- 2N4921
- 2N4922
- 2N4923
- 2N5190
- 2N5191
- 2N5192
- 2N5194
- 2N5195
- 2N5655
- 2N5657
- 2N6034
- 2N6035
- 2N6036
- 2N6038
- 2N6039
- 2N6070A
- 2N6071A
- 2N6071B



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2N6071BT
2N6073A
2N6073B
2N6075
2N6075A
2N6075B
2N6240
BD135
BD136
BD137
BD138
BD139
BD140
BD159
BD179
BD180
BD234
BD237
BD238
BD435
BD435T
BD436
BD436T
BD437
BD437T
BD438
BD438T
BD439
BD440
BD441
BD442
BD675
BD675A
BD676
BD676A
BD677
BD677A
BD678
BD678A
BD679
BD679A
BD680
BD680A
BD680T
BD681
BD682
BD682T
BD776
BD785
BD787
BD788
BD791
BD791T
BUH51
C106B
C106D



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C106D1
C106M
C106M1
C106M1T
MCR106-006
MCR106-008
MCR506-002
MJE13003
MJE170
MJE171
MJE172
MJE180
MJE181
MJE182
MJE200
MJE210
MJE210T
MJE243
MJE253
MJE270
MJE271
MJE340
MJE3439
MJE344
MJE350
MJE371
MJE521
MJE700
MJE702
MJE703
MJE800
MJE802
MJE803
T2322B
TE02514LFVK
TPA0234